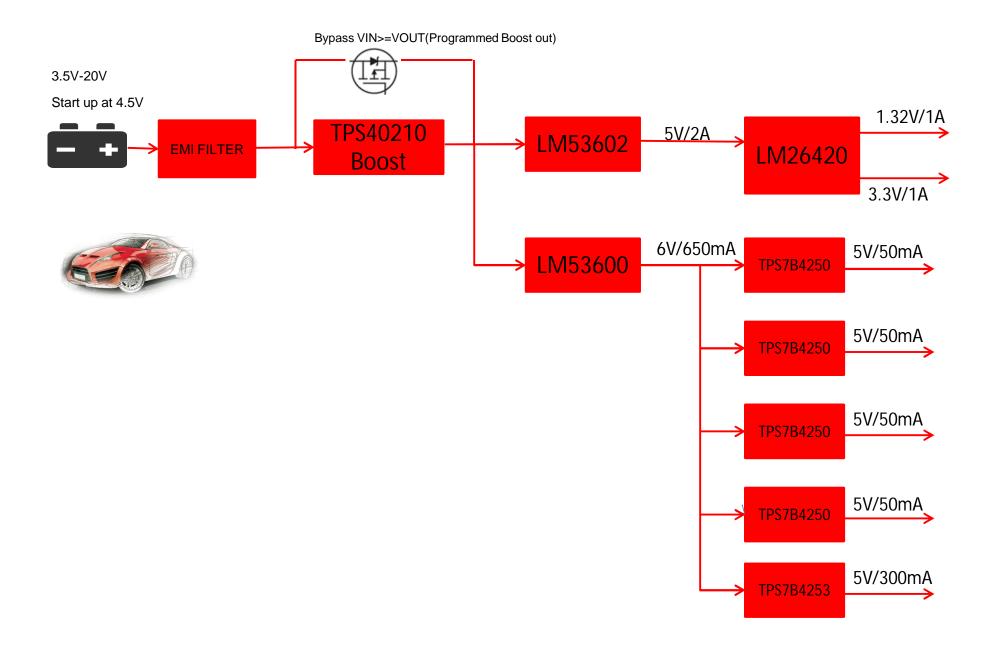
## TIDA-00745\_ BCM Power Reference Design Block Diagram



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